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WHAT IS CLAIMED IS:

- 1. A test vehicle ball grid array package comprising:
- a PCB having bonding fingers;
- an adhesive material being coated on an edge of the PCB;
 - a sealing post being adhered on the adhesive material;
 - a semiconductor testing chip having a plurality of bonding pads adhered on the PCB;
- a plurality of metal wires separately connecting bonding 10 pads of the PCB to the bonding fingers of the PCB;
- a sealing cap adhered on a sealing post for sealing the semiconductor chip; and
- number of plurality of solder balls adhered to a lower side of the solder balls adhered to a lower side of the solder balls adhered to a lower side of the solder balls and the solder balls and the solder balls are solder balls.

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- 2. A test vehicle ball grid array package according to claim 1, wherein each of the sealing post and the sealing cap is made from non-conductive material.
- 20 3. A test vehicle ball grid array package according to claim 1, wherein an extrusion is formed at a upper end of the sealing post.
 - 4. A test vehicle ball grid array package according to

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claim 1, wherein the sealing cap is adhered on the extrusion of the sealing post.

- 5. A test vehicle ball grid array package according to claim 4, wherein the sealing cap is adhered on the extrusion of the sealing post by a low temperature thermoplastic tape or a material similar to low temperature thermoplastic tape.
- 6. A test vehicle ball grid array package according to claim 1, wherein the semiconductor chip is a center pad-type chip or an edge pad-type chip.

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